

NB6L16

2.5 V / 3.3 V Multilevel Input to Differential LVPECL/LVNECL Clock or Data Receiver/ Driver/Translator Buffer

Description

The NB6L16 is a high precision, low power ECL differential clock or data receiver/driver/translator buffer. The device is functionally equivalent to the EL16, EP16, LVEL16 and NBSG16 devices. With output transition times of 70 ps, it is ideally suited for high frequency, low power systems. The device is targeted for Backplane buffering, GbE clock/data distribution, Fibre Channel distribution and SONET clock/data distribution applications.

Input accept LVNECL (Negative ECL), LVPECL (Positive ECL), LVTTL, LVCMOS, CML, or LVDS. Outputs are 800 mV ECL signals.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μ F capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Features

- Input Clock Frequency \geq 6 GHz
- Input Data Rate Frequency \geq 6 Gb/s
- Low 12 mA Typical Power Supply Current
- 70 ps Typical Rise/Fall Times
- 130 ps Input Propagation Delay
- On-Chip Reference for ECL Single-Ended Input – V_{BB} Output
- PECL Mode Operating Range:
 $V_{CC} = 2.375$ V to 3.465 V with $V_{EE} = 0$ V
- NECL Mode Operating Range:
 $V_{CC} = 0$ V with $V_{EE} = -2.375$ V to -3.465 V
- Open Input Default State
- LVDS, LVPECL, LVNECL, LVCMOS, LVTTL and CML Input Compatible
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



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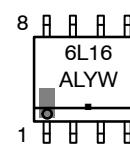


SOIC-8 NB
D SUFFIX
CASE 751-07

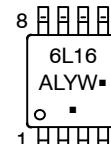


TSSOP-8
DT SUFFIX
CASE 948R-02

MARKING DIAGRAMS*



SOIC-8 NB



TSSOP-8

A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
■ = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note [AND8002/D](#).

ORDERING INFORMATION

Device	Package	Shipping†
NB6L16DG	SOIC-8 NB (Pb-Free)	98 Units / Tube
NB6L16DR2G	SOIC-8 NB (Pb-Free)	2500 Tape & Reel
NB6L16DTG	TSSOP-8 (Pb-Free)	100 Units / Tube
NB6L16DTR2G	TSSOP-8 (Pb-Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

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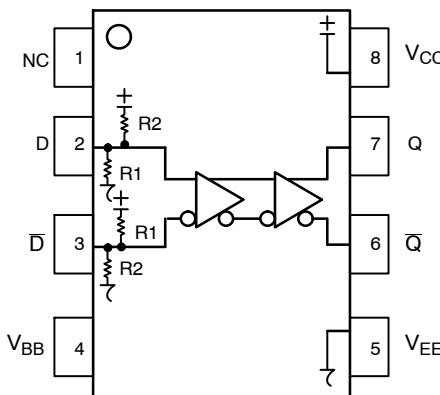


Figure 1. Pinout (Top View) and Logic Diagram

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Default State	Description
1	NC	–	–	No Connect. The NC pin is electrically connected to the die and MUST be left open.
2	D	LVDS, CML, LVPECL, LVNECL, LVTTL, LVCMOS Input	LOW	Non-inverted differential clock/data input. Internal 75 kΩ to V _{CC} and 37.5 kΩ to V _{EE} .
3	D̄	LVDS, CML, LVPECL, LVNECL, LVTTL, LVCMOS Input	HIGH	Inverted differential clock/data input. Internal 37.5 kΩ to V _{CC} and 75 kΩ to V _{EE} .
4	V _{BB}	–	–	Internally generated ECL reference voltage supply.
5	V _{EE}	–	–	Negative power supply voltage.
6	Q̄	ECL Output		Inverted differential ECL output. Typically terminated with 50 Ω resistor to V _{CC} – 2.0 V.
7	Q	ECL Output		Non-inverted differential ECL output. Typically terminated with 50 Ω resistor to V _{CC} – 2.0 V.
8	V _{CC}	–	–	Positive power supply voltage.

Table 2. ATTRIBUTES

Characteristics	Value
Internal Input Default State Resistor (R1)	37.5 kΩ
Internal Input Default State Resistor (R2)	75 kΩ
ESD Protection Human Body Model Machine Model Charged Device Model	> 2 kV > 100 V > 1 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Pb-Free Pkg
SOIC-8 NB TSSOP-8	Level 1 Level 3
Flammability Rating	Oxygen Index: 28 to 34
Transistor Count	UL 94 V-0 @ 1.125 in 167
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note [AND8003/D](#).

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V_{CC}	PECL Mode Power Supply	$V_{EE} = 0 \text{ V}$		3.6	V
V_{EE}	NECL Mode Power Supply	$V_{CC} = 0 \text{ V}$		-3.6	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	$V_{EE} = 0 \text{ V}$ $V_{CC} = 0 \text{ V}$	$V_I \leq V_{CC}$ $V_I \geq V_{EE}$	3.6 -3.6	V
I_{out}	Output Current	Continuous Surge		25 50	mA
V_{INPP}	Differential Input Voltage $ D - \bar{D} $	$V_{CC} - V_{EE} \geq 2.8 \text{ V}$ $V_{CC} - V_{EE} < 2.8 \text{ V}$		2.8 $ V_{CC} - V_{EE} $	V
I_{BB}	V_{BB} Sink/Source			± 0.5	mA
T_A	Operating Temperature Range			-40 to +85	°C
T_{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 NB SOIC-8 NB	190 130	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8 NB	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44	°C/W
T_{sol}	Wave Solder	Standard Pb-Free	$\leq 3 \text{ sec} @ 248^\circ\text{C}$ $\leq 3 \text{ sec} @ 260^\circ\text{C}$	265 265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. DC CHARACTERISTICS, PECL ($V_{CC} = 2.5$ V, $V_{EE} = 0$ V (Note 3))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Negative Power Supply Current (Note 4)	10	12	18	10	12	18	10	12	18	mA
V_{OH}	Output HIGH Voltage (Note 5)	1350	1450	1550	1400	1500	1600	1450	1550	1650	mV
V_{OL}	Output LOW Voltage (Note 5)	565	725	870	630	765	920	690	825	970	mV

DIFFERENTIAL INPUT DRIVEN Single-Ended ((Figures 10, 12) (Note 7))

V_{th}	Input Threshold Reference Voltage Range (Notes 1, 6)	1125		V_{CC} -75	1125		V_{CC} -75	1125		V_{CC} -75	mV
V_{IH}	Single-Ended Input HIGH Voltage	V_{th} +75		V_{CC}	V_{th} +75		V_{CC}	V_{th} +75		V_{CC}	mV
V_{IL}	Single-Ended Input LOW Voltage	V_{EE}		V_{th} -75	V_{EE}		V_{th} -75	V_{EE}		V_{th} -75	mV

DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY ((Figures 11, 13) (Note 8))

V_{IHD}	Differential Input HIGH Voltage	1200		V_{CC}	1200		V_{CC}	1200		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage	V_{EE}		V_{CC} -75	V_{EE}		V_{CC} -75	V_{EE}		V_{CC} -75	mV
V_{CMR}	Input Common Mode Range (Differential Cross-Point Voltage) (Note 2)	950		V_{CC} -38	950		V_{CC} -38	950		V_{CC} -38	mV
V_{ID}	Differential Input Voltage ($V_{IHD} - V_{ILD}$)	75		2500	75		2500	75		2500	mV
I_{IH}	Input HIGH Current D \bar{D}		50 10	150 150		50 10	150 150		50 10	150 150	μA
I_{IL}	Input LOW Current D \bar{D}		-150 -150	-5 -30		-150 -150	-5 -30		-150 -150	-5 -30	μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. V_{th} is applied to the complementary input when operating in Single-Ended mode.
2. V_{CMR} minimum varies 1:1 with V_{EE} , V_{CMR} maximum varies 1:1 with V_{CC} .
3. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.125 V to -1.3 V.
4. All input and output pins left open.
5. All loading with 50Ω to $V_{CC} - 2.0$ V.
6. Do not use V_{BB} as a reference voltage for Single-Ended PECL signals when operating device at $V_{CC} - V_{EE} < 3.0$ V.
7. V_{th} , V_{IH} , and V_{IL} parameters must be complied with simultaneously.
8. V_{IHD} , V_{ILD} , V_{ID} and V_{CMR} parameters must be complied with simultaneously.

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Table 5. DC CHARACTERISTICS, PECL ($V_{CC} = 3.3$ V, $V_{EE} = 0$ V (Note 3))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Negative Power Supply Current (Note 4)	10	12	18	10	12	18	10	12	18	mA
V_{OH}	Output HIGH Voltage (Note 5)	2150	2250	2350	2200	2300	2400	2250	2350	2450	mV
V_{OL}	Output LOW Voltage (Note 5)	1365	1525	1670	1430	1565	1720	1490	1625	1770	mV

DIFFERENTIAL INPUT DRIVEN Single-Ended ((Figures 10, 12) (Note 6))

V_{th}	Input Threshold Reference Voltage Range (Note 1)	1125		V_{CC} -75	1125		V_{CC} -75	1125		V_{CC} -75	mV
V_{IH}	Single-Ended Input HIGH Voltage	V_{th} +75		V_{CC}	V_{th} +75		V_{CC}	V_{th} +75		V_{CC}	mV
V_{IL}	Single-Ended Input LOW Voltage	V_{EE}		V_{th} -75	V_{EE}		V_{th} -75	V_{EE}		V_{th} -75	mV
V_{BB}	Output Voltage Reference	1880	1980	2070	1880	1980	2070	1880	1980	2070	mV

DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY ((Figures 11, 13) (Note 7))

V_{IHD}	Differential Input HIGH Voltage	1200		V_{CC}	1200		V_{CC}	1200		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage	V_{EE}		V_{CC} -75	V_{EE}		V_{CC} -75	V_{EE}		V_{CC} -75	mV
V_{CMR}	Input Common Mode Range (Differential Cross-Point Voltage) (Note 2)	950		V_{CC} -38	950		V_{CC} -38	950		V_{CC} -38	mV
V_{ID}	Differential Input Voltage ($V_{IHD} - V_{ILD}$)	75		2500	75		2500	75		2500	mV
I_{IH}	Input HIGH Current D D		50 10	150 150		50 10	150 150		50 10	150 150	μA
I_{IL}	Input LOW Current D D	-150 -150	-5 -30		-150 -150	-5 -30		-150 -150	-5 -30		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. V_{th} is applied to the complementary input when operating in Single-Ended mode.
2. V_{CMR} minimum varies 1:1 with V_{EE} , V_{CMR} maximum varies 1:1 with V_{CC} .
3. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925 V to -0.5 V.
4. All input and output pins left open.
5. All loading with 50Ω to $V_{CC} - 2.0$ V.
6. V_{th} , V_{IH} , and V_{IL} parameters must be complied with simultaneously.
7. V_{IHD} , V_{ILD} , V_{ID} and V_{CMR} parameters must be complied with simultaneously.

Table 6. DC CHARACTERISTICS, NECL ($V_{CC} = 0$ V, $V_{EE} = -3.465$ V to -2.375 V (Note 3))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Negative Power Supply Current (Note 5)	10	12	18	10	12	18	10	12	18	mA
V_{OH}	Output HIGH Voltage (Note 4)	-1150	-1050	-950	-1100	-1000	-900	-1050	-950	-850	mV
V_{OL}	Output LOW Voltage (Note 4)	-1935	-1775	-1630	-1870	-1735	-1580	-1810	-1675	-1530	mV

DIFFERENTIAL INPUT DRIVEN Single-Ended ((Figures 10, 12) (Note 6))

V_{th}	Input Threshold Reference Voltage Range (Note 1)	V_{EE} +1125		V_{CC} -75	V_{EE} +1125		V_{CC} -75	V_{EE} +1125		V_{CC} -75	mV
V_{IH}	Single-Ended Input HIGH Voltage	V_{th} +75		V_{CC}	V_{th} +75		V_{CC}	V_{th} +75		V_{CC}	mV
V_{IL}	Single-Ended Input LOW Voltage	V_{EE}		V_{th} -75	V_{EE}		V_{th} -75	V_{EE}		V_{th} -75	mV
V_{BB}	Output Voltage Reference	-1420	-1320	-1230	-1420	-1320	-1230	-1420	-1320	-1230	mV

DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY ((Figures 11, 13) (Note 7))

V_{IHD}	Differential Input HIGH Voltage	V_{EE} +1200		V_{CC}	V_{EE} +1200		V_{CC}	V_{EE} +1200		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage	V_{EE}		V_{CC} -75	V_{EE}		V_{CC} -75	V_{EE}		V_{CC} -75	mV
V_{CMR}	Input Common Mode Range (Differential Cross-Point Voltage) (Note 2)	V_{EE} +950		V_{CC} -38	V_{EE} +950		V_{CC} -38	V_{EE} +950		V_{CC} -38	mV
V_{ID}	Differential Input Voltage ($V_{IHD} - V_{ILD}$)	75		2500	75		2500	75		2500	mV
I_{IH}	Input HIGH Current $\frac{D}{D}$		50 10	150 150		50 10	150 150		50 10	150 150	μA
I_{IL}	Input LOW Current $\frac{D}{D}$	-150 -150	-5 -30		-150 -150	-5 -30		-150 -150	-5 -30		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. V_{th} is applied to the complementary input when operating in Single-Ended mode.
2. V_{CMR} minimum varies 1:1 with V_{EE} , V_{CMR} maximum varies 1:1 with V_{CC} .
3. Input and output parameters vary 1:1 with V_{CC} .
4. All loading with 50Ω to $V_{CC} - 2.0$ V.
5. All input and output pins left open.
6. V_{th} , V_{IH} , and V_{IL} parameters must be complied with simultaneously.
7. V_{IHD} , V_{ILD} , V_{ID} and V_{CMR} parameters must be complied with simultaneously.

Table 7. AC CHARACTERISTICS ($V_{CC} = 0 \text{ V}$; $V_{EE} = -3.465 \text{ V}$ to -2.375 V or $V_{CC} = 2.375 \text{ V}$ to 3.465 V ; $V_{EE} = 0 \text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OUTPP}	Output Voltage Amplitude $f_{IN} < 3 \text{ GHz}$ $f_{IN} < 6 \text{ GHz}$ (See Figures 2 & 3)	500 270	700 350		500 270	700 350		500 270	700 300		mV
t_{DATA}	Maximum Operating Data Rate	6									Gb/s
t_{PLH}, t_{PHL}	Propagation Delay to Output Differential @ 1 GHz	80	130	180	80	130	180	85	135	185	ps
t_{SKEW}	Duty Cycle Skew (Note 2) Device-to-Device Skew		3 30	25 60		3 30	25 60		3 30	25 60	ps
t_{JITTER}	RMS Random Clock Jitter $f_{IN} < 6 \text{ GHz}$ (Note 3) Peak-to-Peak Data Dependent Jitter $f_{IN} < 6 \text{ Gb/s}$ (Note 4)		0.2 2	1 12		0.2 2	1 12		0.2 2	1 12	ps
V_{INPP}	Input Voltage Swing / Sensitivity (Differential Configuration) (Note 5)	75	700	2500	75	700	2500	75	700	2500	mV
t_r, t_f	Output Rise/Fall Times Q, \bar{Q} (20%–80%)	30	70	120	30	70	120	30	70	120	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Measured using a 800 mV source, 50% duty cycle clock source. All loading with 50Ω to V_{CC} . Input edge rates 40 ps (20% – 80%).
2. See Figure 9 $t_{skew} = |t_{PLH} - t_{PHL}|$ for a nominal 50% differential clock input waveform. Skew is measured between outputs under identical transitions and conditions @ 1 GHz.
3. Additive RMS jitter with 50% duty cycle clock signal at 6 GHz.
4. Additive Peak-to-Peak data dependent jitter with NRZ PRBS $2^{23}-1$ data rate at 6 Gb/s.
5. $V_{INPP(max)}$ cannot exceed $V_{CC} - V_{EE}$. (Applicable only when $V_{CC} - V_{EE} < 2500 \text{ mV}$). Input voltage swing is a single-ended measurement operating in the differential mode.

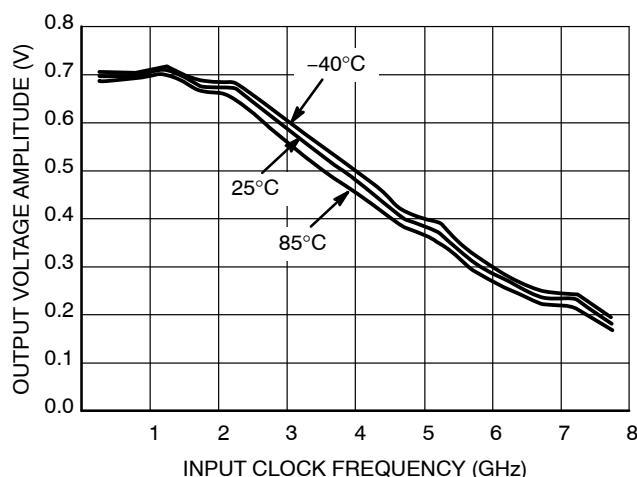


Figure 2. Output Voltage Amplitude (V_{OUTPP}) versus Input Clock Frequency (f_{IN}) and Temperature at $V_{CC} - V_{EE} = 3.3 \text{ V}$

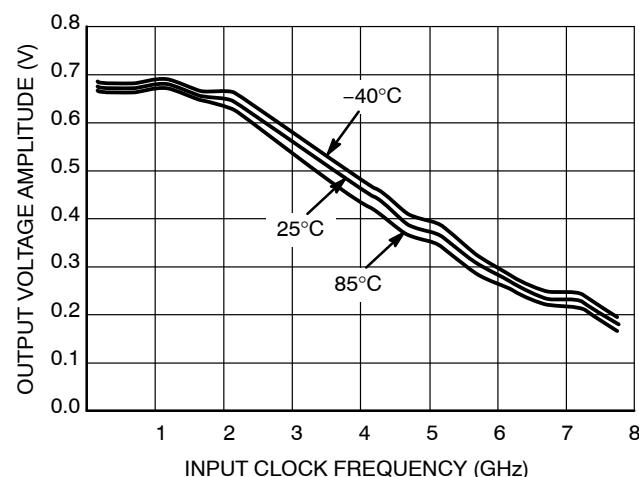


Figure 3. Output Voltage Amplitude (V_{OUTPP}) versus Input Clock Frequency (f_{IN}) and Temperature at $V_{CC} - V_{EE} = 2.5 \text{ V}$

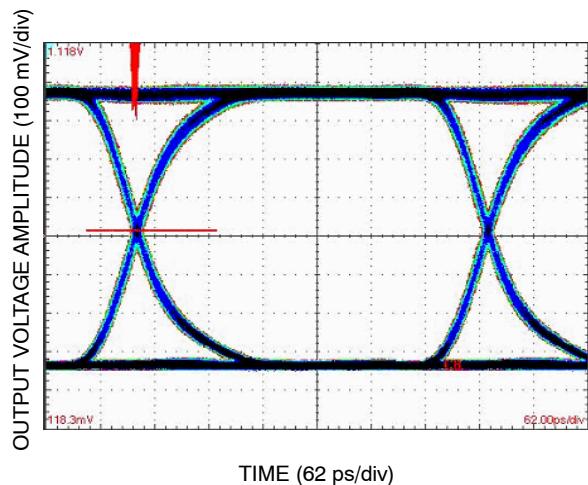


Figure 4. Typical Output Waveform at 2.488 Gb/s with PRBS 2²³-1 (Total System Pk-Pk Jitter is 16 ps. Device Pk-Pk Jitter Contribution is 3 ps)

NOTE: $V_{CC} - V_{EE} = 3.3$ V; $V_{IN} = 700$ mV; $T_A = 25^\circ\text{C}$.

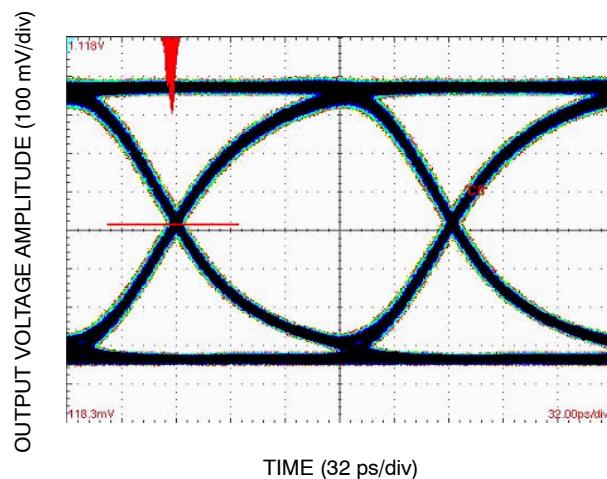


Figure 5. Typical Output Waveform at 6.125 Gb/s with PRBS 2²³-1 (Total System Pk-Pk Jitter is 17 ps. Device Pk-Pk Jitter Contribution is 4 ps)

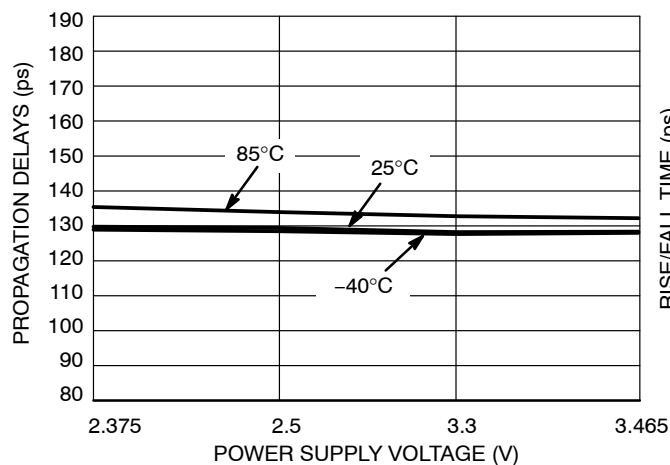


Figure 6. Propagation Delay versus Power Supply Voltage and Temperature

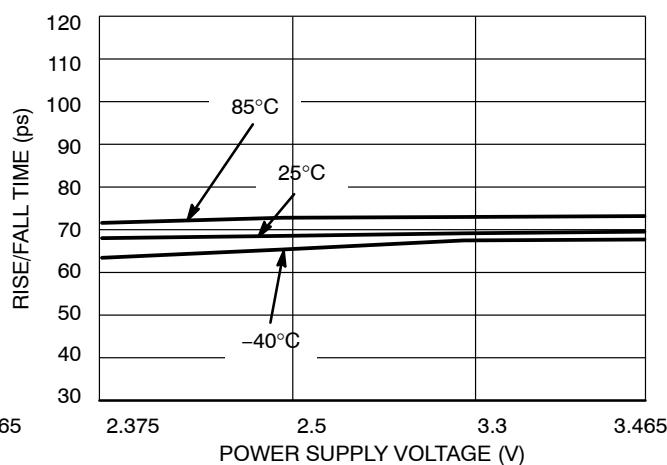


Figure 7. Rise/Fall Time versus Power Supply Voltage and Temperature

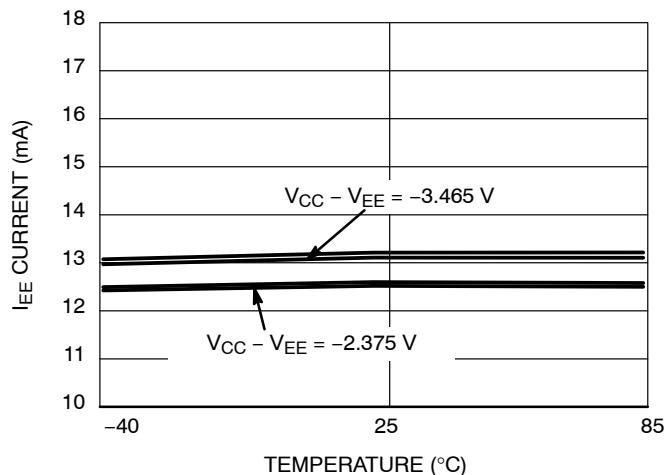


Figure 8. I_{EE} Current versus Temperature and Power Supply Voltage

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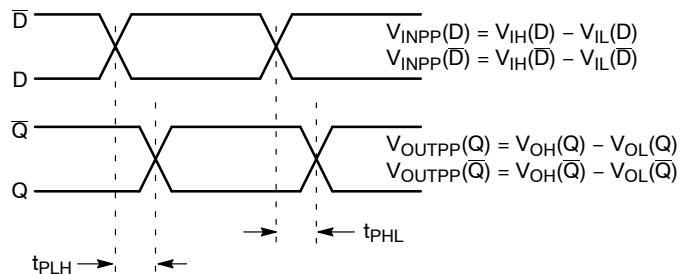


Figure 9. AC Reference Measurement

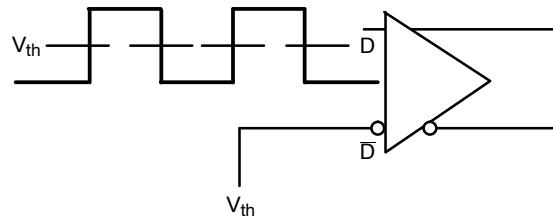


Figure 10. Differential Input Driven Single-Ended

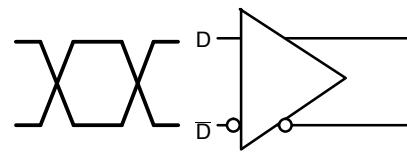


Figure 11. Differential Inputs Driven Differentially

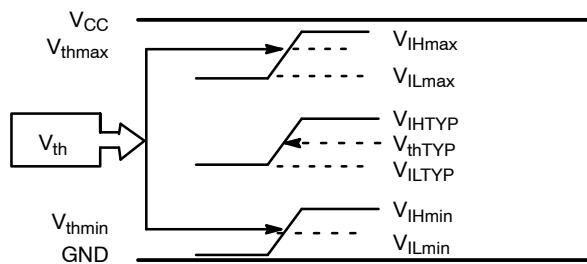


Figure 12. V_{th} Diagram

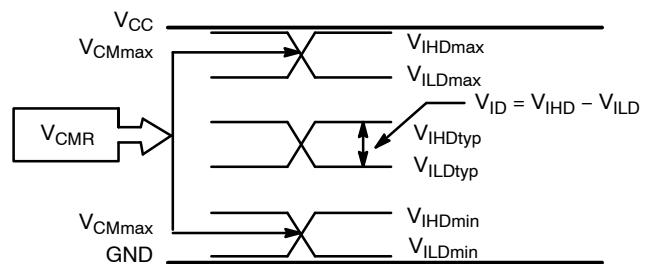
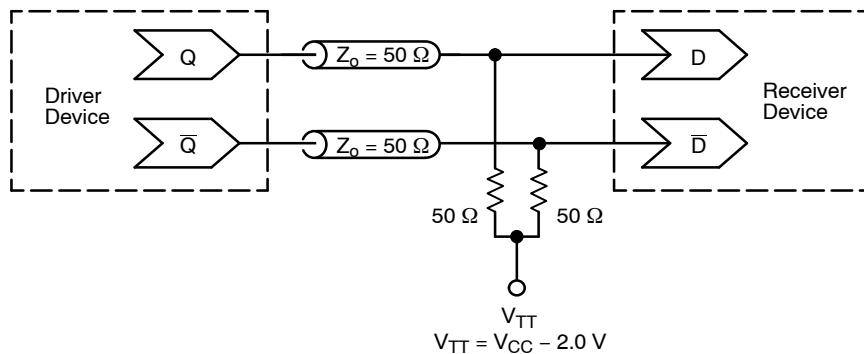


Figure 13. V_{CMR} Diagram

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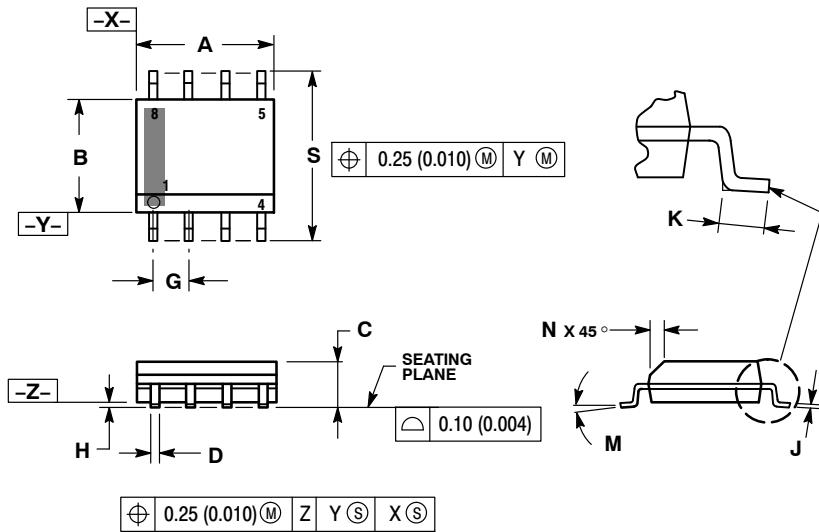
**Figure 14. Typical Termination for Output Driver and Device Evaluation
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices)**

Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

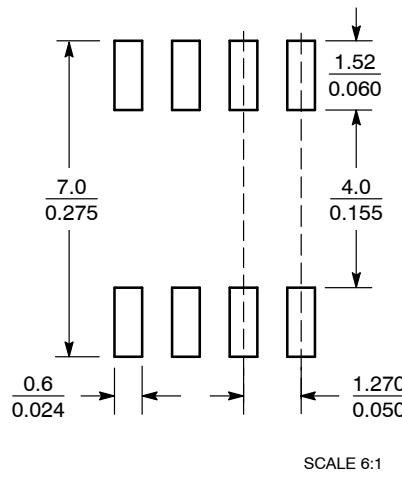
**SOIC-8 NB
D SUFFIX
CASE 751-07
ISSUE AK**



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	BSC	0.050	BSC
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

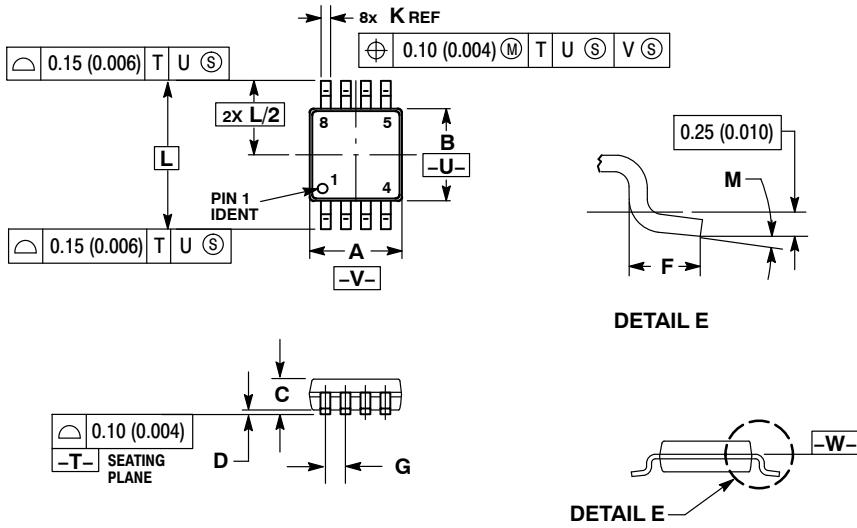


SCALE 6:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

**TSSOP-8
DT SUFFIX
CASE 948R-02
ISSUE A**

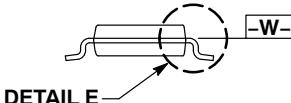


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

DETAIL E



DETAIL E

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